

VOC503 NO CLEAN FLUX

GENERAL DESCRIPTION

VOC503 VOC Free Flux is a halide-free, no clean activated material for wave soldering through-hole, mixed and surface mount assemblies. VOC503 eliminates solder balls while providing excellent solderability with minimal flux residue so that cleaning is not necessary. VOC503 was formulated especially for Organic Surface Preservative (OSP) coated P.C. boards, which are difficult to solder after multiple passes through reflow solder processes.

FLUX CONTROL

- The amount of flux to be applied during **foaming applications** should be between 800 and 1300 micrograms per square inch of circuit. The amount of flux to be applied during **spray application** should be between 475 and 850 micrograms per square inch of circuit.

SPRAY SYSTEMS

- VOC503 is suitable and enhanced by the use of a total loss spray system.
- Ideally an air knife should be fitted even when using a spray system in order to prevent insufficient capillary action when soldering. Spray system air knives should normally be angled slightly towards the system. Excessive white deposits on the topside of the board are usually attributable to excess flux application. Adjustment of the air knife angle, air volume, and pressure can rectify excessive white deposits.

FOAMING SYSTEMS

- The air knife hole diameter should be between 1 and 1.5 mm and the distance from the fluxer to the air knife should be approximately 4 to 6 inches. The air knife should be angled between 5 to 12 degrees away from the foam wave so that excess flux can be removed without destroying the foam head.

CONVEYOR SPEED

- The ideal conveyor speed is dependent on the type of board and preheat requirements, but a speed between 3.5 to 5.5 feet/minute will suit most applications.

STORAGE AND HANDLING

Use in well-ventilated area and observe standard precautions for handling and use. Refer to the Material Safety Data Sheet for further information.

PROCESS CONSIDERATIONS

• PREHEAT

A topside temperature between 90 and 130 degrees Celsius is recommended.

A bottom side temperature should be 25 degrees Celsius higher than the topside.

• SOLDER TEMPERATURE

A solder temperature of 255°-270° Celsius should be maintained for SN100C Lead Free Solder.

A solder temperature of 245°-255° Celsius should be maintained for Sn63/Pb37 Leaded Solder

• THINNING

Flux maintenance is much simpler with VOC Free fluxes as evaporative loss in a foam flux process is much less than with an alcohol based flux. No thinning is generally required in normal foam flux use.

STANDARD PRODUCT AVAILABILITY

UNIT OF MEASURE
1 GALLON JUG
5 GALLON PAIL
55 GALLON DRUM

SAFETY

VOC503 FLUX is formulated for foam, spray, wave or dip applications. VOC503 is suitable for conventional, mixed, and surface mount technologies for telecommunications, computer and general consumer electronics.

Before use read all material safety data information. Previously used flux should be thoroughly cleaned out of the system since small amounts can reduce the performance of the VOC503. Conveyors, pallets and fingers should be cleaned. During extended periods of time such as nights and weekends the flux should be removed from the machine and stored in a sealed container. The air stone should be left soaking in FCT Assembly thinners (FT100) and changed before the quality of the foam deteriorates. It is recommended that you use a new stone when replacing Rosin type fluxes. A program should be established for the regular replacement of the flux to avoid the build up of contaminants within the flux. For optimal soldering consistency, the flux should be disposed of once every 40 hours of operation.

CLEANING

VOC503 flux properly applied and processed leaves no discernible residues without cleaning.

It is recommended that the soldering system itself be tested for cleanliness using an un-fluxed board passed over the wave soldering machine. Suppliers should be requested to supply clean components and clean boards with good solderability.

Special applications may have regulations insisting on board cleaning and in such cases the residues from VOC503 can be effectively removed with hot deionized water (120-140°C) in either an in-line washer or batch cleaner. No additional soap or saponifier is required unless there are other contaminants present. Machine contamination will in any case be much less than with conventional rosin fluxes. VOC503 flux may be slightly corrosive towards some metal PCB handling equipment.

PROPERTIES

Properties	Values
Solids Content	6 - 7%
Specific Gravity at 20 degrees C	1.00 - 1.03
Acid Number (mgKOH/gm)	40 - 50
Color	Clear to light yellow
Copper mirror	High activity
Halide Content	0.00%
Silver chromate	No halides
Fluoride test	None detected
Ion chromatography	No halides
J-STD-004 Designation	ORH0

MATERIAL SAFETY DATA SHEETS

Material Safety Data Sheets (MSDS) are available online at www.fctassembly.com

